

INTERNATIONAL STANDARD

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**Thermal standardization on semiconductor packages –
Part 3: Thermal circuit simulation models of discrete semiconductor packages
for transient analysis**

**Normalisation thermique des boîtiers de semiconducteurs –
Partie 3: Modèles de simulation de circuits thermiques de boîtiers de
semiconducteurs discrets pour analyse transitoire**

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THERMAL STANDARDIZATION ON SEMICONDUCTOR PACKAGES –

Part 3: Thermal circuit simulation models of discrete semiconductor packages for transient analysis

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The text of this International Standard is based on the following documents:

Draft	Report on voting
47D/967/CDV	47D/979/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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